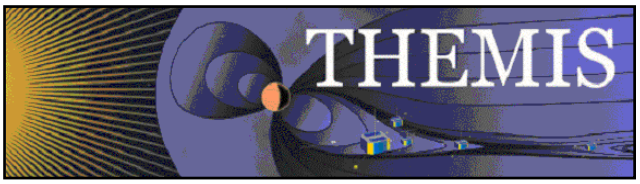

THEMIS
Radial EFI (Electric Field Instrument) Boom
Interface Control Document (ICD)

thm_sys_108AD_SPB_ICD.doc
Version: AD
Release: 11 March 2005

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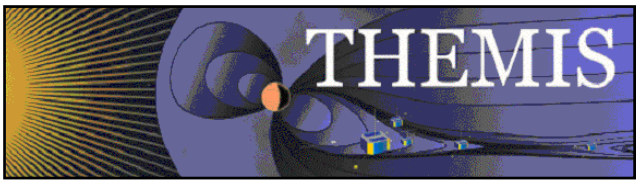

Document Revision Record

Rev.	Date	Description of Change	Approved By
D1	28 AUG 2003	Preliminary Draft	-
D2	13 OCT 2003	Second Draft	-
-	31 MAR 2004	Final Release: Updated per ICD drawings. Updated Thermal Sections.	
AA	25 MAY 2004	Baseline: Updated per Swales comments Appended Mechanical ICD Drawings	
AB	04 OCT 2004	Updated Mechanical ICD Drawing	
AC	11 JAN 2005	Updated Mechanical ICD Drawing	
AD	11 MAR 2005	Removed thermal information which has been relocated to the THEMIS Instrument Thermal Specification, THM_SYS_119_ITH_ICD	

Drawing Revision Record

Rev.	Date	Description of Change	Approved By
AA	5/25/04	THM-SPB-ICD-001 Baseline Release	
AB	09/29/04	THM-SPB-ICD-001 Rev AB	
AC	01/07/05	THM-SPB-ICD-001 Rev AC	
AD	03/11/05	Updated and improved thermal information Signature Page: Updated the Swales Systems Lead	

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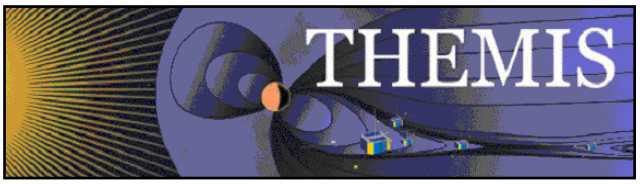

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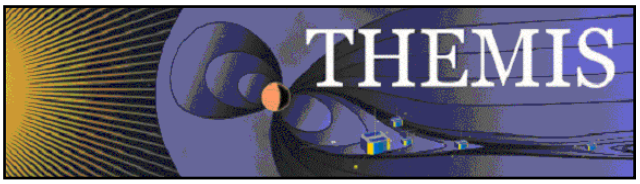
TBD List

Identifier	Description
TBR	Connection is bolted only; no pinning or other hardware is required



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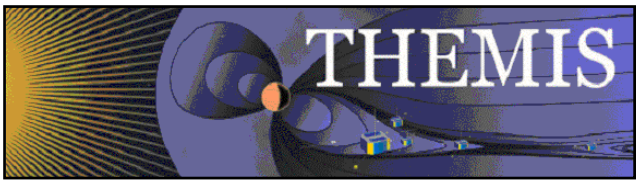
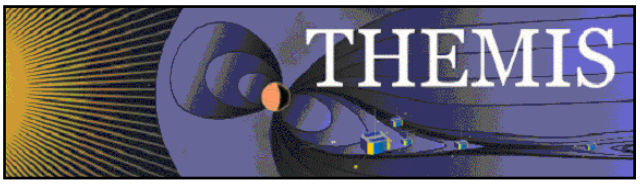




1. Introduction

This document shall describe the interface between the THEMIS probe bus and the Radial EFI Booms. Each THEMIS probe shall carry 4 Radial EFI Booms; each Boom is identical to each other. All attach interfaces to the probe bus are identical with the exception of the orientation of the Boom to the Solar Panels.

1.1 Scope

This Interface Control Document (ICD) will define the flight hardware interface requirements, mechanical and thermal model requirements, data/information deliverables, GSE/Developmental unit requirements, and Verification Matrix with Verification requirements. Functional/Performance requirements are found in the requirements database, and Environmental requirements are found in the Verification Plan and Environmental Specification.

1.2 Component Description

The EFI measures the 3D electric field in the frequency band from DC to 300 kHz. The four Radial EFI instruments are suspended at the end of the wire booms approximately 20 to 25 meters from the probe center in the spin plane and are stabilized by centrifugal force. Each deployed Boom is perpendicular to two other booms and in-line with the last.

1.3 Document Conventions

In this document, TBD (To Be Determined) means that no data currently exists. A value followed by TBR (To Be Resolved) means that this value is preliminary. In either case, the value is typically followed by UCB (University of California at Berkeley) and /or SA (Swales Aerospace) indicating who is responsible for providing the data, and a unique reference number.

1.4 Applicable Documents

The following documents include drawings and THEMIS Project policies, and are part of the Interface Requirements. In the event of a conflict between this ICD and the following documents, this ICD takes precedence. All ICD documents and drawings can be found on the Berkeley THEMIS FTP site:
ftp://apollo.ssl.berkeley.edu/pub/THEMIS/

1. THEMIS SPB Interface Drawing, File THM-SPB-ICD-001
2. THEMIS Instrument Thermal Specification, THM_SYS_119_ITH_ICD

The following documents are government documents, provided as references for the Interface Requirements.

1. EWR-127-1: Eastern and Western Range Safety Requirements
2. MIL-HDBK-340A: Application Guidelines for MIL-STD-1540; Test Requirements for Launch, Upper Stage, and Space Vehicles
3. MIL-STD-1522A: Standard General Requirements for Safe Design and Operation of Pressurized Missile and Space Systems
4. MIL-STD-1540D: Product Verification Requirements for Launch, Upper-stage, and Space Vehicles
5. NPG 6000.1E: Requirements for Packaging, Handling and Transportation for Aeronautical and Space Systems, Equipment, and Associated Components, dated April 26, 1999

1.5 Units

The drawings contained in this document are dual dimensioned, inches (mm).

2. Mechanical Interface

2.1 Interface Drawing

The mechanical configuration of the radial EFIs is shown in the SPB Interface Drawing THM-SPB-ICD-001. These include a dimensioned drawing detailing envelope, mounting, and connector locations, CG location, coordinates, thermal surface finishes, and thermal interface reference.

2.1.1 Instrument Envelopes

The envelope specified is the static envelope, inclusive of all instrument hardware and blankets. The actual flight instrument as delivered to Swales is to be within this envelope. Dynamic deflections of the instrument in Launch Mode will be accounted for by Swales as long as the instrument minimum frequency requirement is met. The Radial EFI Boom instrument and overall envelope geometry and dimensions are as shown in THM-SPB-ICD-001.

2.1.1.1 Instrument Stowed Envelope

The Instrument interface drawings listed below are the controlling references that specify the Launch mode mechanical interfaces: THM-SPB-ICD-001.

2.1.1.2 Instrument Deployed Envelope

The Instrument interface drawings listed below are the controlling references that specify the On-Orbit mode mechanical interfaces: THM-SPB-ICD-001.

2.2 Coordinate Systems

The instrument coordinate system relative to the instrument interface is shown in the interface drawing THM-SPB-ICD-001. All instrument information is defined relative to this Instrument coordinate system.

2.3 Field of View

2.3.1 Field of View

The Instrument Interface Drawing, THM-SPB-ICD-001 is the controlling reference that specifies the On-Orbit mode Fields of View.

2.3.2 Field of Travel

The Boom interface drawings listed below are the controlling references that specify the On-Orbit mode Fields of Travel: THM-SPB-ICD-001.

2.4 Mass Properties

The mass of the SPB shall be measured prior to delivery to within $\pm$0.01kg. The Center of Gravity (CG), as documented in THM-SPB-ICD-001 and referenced to the Instrument coordinate axes described there, shall be predicted through analysis. The stowed and deployed Moments of Inertia (MOIs) of General Instrument, as documented in THM-SPB-ICD-001 and referenced to the Instrument coordinate axes described above, shall be predicted through analysis.

2.5 Mounting

2.5.1 Mounting Method

The Instrument shall be mounted to the Probe Bus using a bolt pattern on a single interface plane, consisting of 4 bolts, washers and thermal isolators mounted to the attach feet of the Radial EFI Boom (through holes) into inserts in the deck of the S/C. Bolt Pattern as shown in UCB Drawing THM-SPB-ICD-001. All bolts to be 8-32 UNC sized. Connection is bolted only; no pinning or other hardware is required (TBR).

2.5.2 Mounting Interface

Mounting hole coordinates, dimensions, orientation, and tolerances are shown in Drawing THM-SPB-M107. Mounting hole tolerances shall be dimensioned in accordance with ANSI Standard Y14.5M, "Dimensioning and Tolerancing", 1999 or later revisions.

2.5.3 Mounting Hardware

Swales will provide all fasteners and shims as required to meet alignment requirements.

2.5.4 Mounting Surface Requirements

2.5.4.1 Flatness

The mounting surface of the instrument shall be fabricated to a flatness tolerance of 0.002 inches or less to ensure the required electrical and thermal contacts as well as

the required alignment accuracy. The Probe Bus mounting surface shall be flat to the tolerance 0.015 inches or less. Instrument mounting surface characteristics shall be documented in the instrument interface drawing THM-SPB-ICD-001. Swales shall shim as required to avoid inducing stress.

2.5.4.2 Surface Finish

The mounting surface of the instrument shall be fabricated to a surface finish of 32 micro-inches RMS or less to ensure the required electrical and thermal contacts as well as the required alignment accuracy.

2.5.5 Mounting Location

The SPB locations are determined by Swales.

2.5.6 Drill Templates

No drill templates will be required. All Radial EFI Boom interfaces will match if all conditions of this specification are maintained at all interfaces.

2.5.7 Probe Mounting

2.5.7.1 Orientation During Integration

Instruments shall be capable of being installed/removed with the Probe Bus X/Y axes horizontal.

2.5.7.2 Mounting Impacts

The Instrument Components shall be capable of being installed or removed during ground operations without degradation, damage or disqualification of the flight hardware. Note the Radial EFI Boom assembly will protrude through the Solar Panels.

2.6 Alignment.

2.6.1 Alignment Responsibilities

Swales is responsible for aligning the instrument to the bus. The Instrument is responsible for aligning the sensing elements to the interface plate.

2.6.2 Alignment Requirements

The SPB shall be placed relative to the bus coordinate system within mounting bolt-hole tolerances.

2.7 Mechanisms

2.7.1 Radial Boom Deploy Mechanism

The Radial EFI Booms are wire Booms that deploy the sensor by way of a wire tether that is released when the wire is unwound from a spool by a motorized metering wheel.

2.8 Access To Instrument

2.8.1 General Access

All items to be installed, removed, or replaced at the Probe Bus/Carrier level shall be accessible without disassembly of the item.

2.8.2 Specific Access

The following table provides a list of test connectors, contamination covers, and any other I&T equipment that must be installed or removed during integration, environmental test or at the launch site.

Table 2.8.2: Access Requirements

Item	Last Access	Function
IDPU Actuator Enabling Plug	Launch Site: Probe Carrier Assembly	Provides lock-out of all boom actuator power for mechanical safing
EFI Boom Enabling Plug	Launch Site: Probe Carrier Assembly	Provides Boom lock-out and test capability.

Test Items: All items to be removed prior to test shall be tagged with a red tag stating, “REMOVE BEFORE TEST”. All items to be installed prior to test shall be tagged with a green tag.

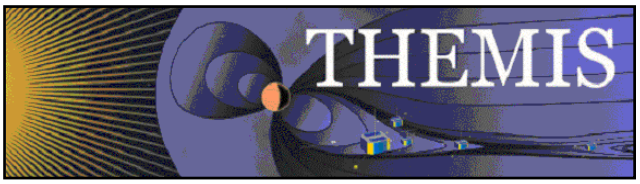
Flight Items: All items to be removed prior to flight shall be tagged with a red tag stating, “REMOVE BEFORE FLIGHT”. All items to be installed prior to flight shall be tagged with a green tag.

2.8.3 Mechanical Test Instrumentation Access

The Instrument shall accommodate mounting area and access to temporarily installed acceleration sensors and supporting hardware for purposes of monitoring accelerations during Instrument, Probe Bus, and Probe Carrier Assembly ground test.

3. Thermal Interface

Thermal interface information has been transferred to Ref 11 THEMIS Instrument Thermal Specification, THM_SYS_119_ITH_ICD



3.1 Thermal Design

This section has been moved to Reference 11.

3.2 Thermal Design & Analysis Responsibilities

This section has been moved to Reference 11.

3.3 Heat Transfer

This section has been moved to Reference 11.

3.4 Power Dissipation

The nominal and maximum power dissipation is provided in THM_SYS_009. Power levels used in thermal modeling are given in Reference 11

3.5 Temperature Requirements

This section has been moved to Reference 11.

3.6 Temperature Monitoring and Control

This section has been moved to Reference 11.

3.7 Contamination Control

This section has been moved to Reference 11.

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